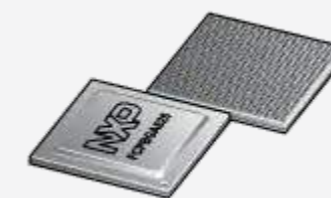


M86261G12 (Active)

C2K 650MHz Device with options: 8 VOIP channels USB2.0, USB3.0 ECC RGMII (X2) SPI (X1)



Package:
[FBGA625](#)
 FBGA625, plastic, fine-pitch ball grid array; 625 balls; 0.8 mm pitch; 21 mm x 21 mm x 2.35 mm body

[Buy Options](#) | [Environmental Information](#) | [Quality Information](#) | [Shipping Information](#)

Buy Options

M86261G12
 935325894557

Active ⓘ

TRAY-Tray, Bakeable, Multiple in Drypack
 Min. Package Quantity: 60
 Lead Time: 12 weeks

[Distributor](#)

100 @ US
\$22.02

Environmental Information

Material Declaration	PbFree	EU RoHS	Halogen Free	RHF Indicator	2nd Level Interconnect	REACH SVHC	Weight (mg)
M86261G12 (935325894557)	Yes	Yes	Yes	D	e1	REACH SVHC	3110.0

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
M86261G12 (935325894557)	No	3	250	30

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)	CCATS
M86261G12 (935325894557)	854231	5A002A1	G142070

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